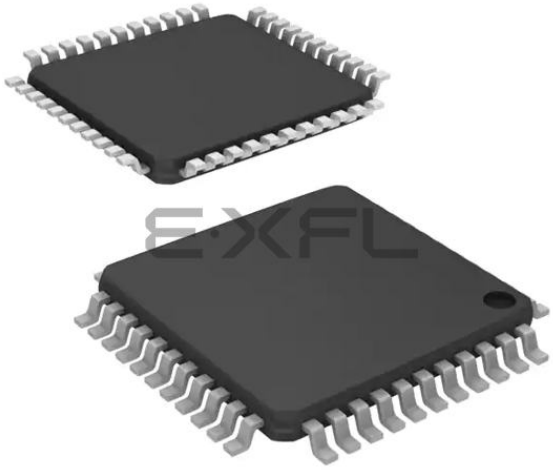

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	AC'97, Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj128gp204-e-pt

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2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 family of 16-bit Digital Signal Controllers (DSCs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used)
  (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
  (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used
  (see **Section 2.6 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins used when external voltage reference for ADC module is implemented

Note: The AVDD and AVSS pins must be connected independent of the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

TABLE 4-13: ADC1 REGISTER MAP FOR dsPIC33FJ64GP202/802, dsPIC33FJ128GP202/802 AND dsPIC33FJ32GP302

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC1BUF0	0300	ADC Data Buffer 0																xxxx
AD1CON1	0320	ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM<1:0>		SSRC<2:0>			—	SIMSAM	ASAM	SAMP	DONE	0000
AD1CON2	0322	VCFG<2:0>			—	—	CSCNA	CHPS<1:0>		BUFS	—	SMPI<3:0>				BUFM	ALTS	0000
AD1CON3	0324	ADRC	—	—	SAMC<4:0>					ADCS<7:0>								0000
AD1CHS123	0326	—	—	—	—	—	CH123NB<1:0>		CH123SB	—	—	—	—	—	CH123NA<1:0>		CH123SA	0000
AD1CHS0	0328	CH0NB	—	—	CH0SB<4:0>					CH0NA	—	—	CH0SA<4:0>					0000
AD1PCFGL	032C	—	—	—	PCFG12	PCFG11	PCFG10	PCFG9	—	—	—	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0	0000
AD1CSSL	0330	—	—	—	CSS12	CSS11	CSS10	CSS9	—	—	—	CSS5	CSS4	CSS3	CSS2	CSS1	CSS0	0000
AD1CON4	0332	—	—	—	—	—	—	—	—	—	—	—	—	—	DMABL<2:0>			0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-14: ADC1 REGISTER MAP FOR dsPIC33FJ64GP204/804, dsPIC33FJ128GP204/804 AND dsPIC33FJ32GP304

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC1BUF0	0300	ADC Data Buffer 0																xxxx
AD1CON1	0320	ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM<1:0>		SSRC<2:0>			—	SIMSAM	ASAM	SAMP	DONE	0000
AD1CON2	0322	VCFG<2:0>			—	—	CSCNA	CHPS<1:0>		BUFS	—	SMPI<3:0>				BUFM	ALTS	0000
AD1CON3	0324	ADRC	—	—	SAMC<4:0>					ADCS<7:0>								0000
AD1CHS123	0326	—	—	—	—	—	CH123NB<1:0>		CH123SB	—	—	—	—	—	CH123NA<1:0>		CH123SA	0000
AD1CHS0	0328	CH0NB	—	—	CH0SB<4:0>					CH0NA	—	—	CH0SA<4:0>					0000
AD1PCFGL	032C	—	—	—	PCFG12	PCFG11	PCFG10	PCFG9	PCFG8	PCFG7	PCFG6	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0	0000
AD1CSSL	0330	—	—	—	CSS12	CSS11	CSS10	CSS9	CSS8	CSS7	CSS6	CSS5	CSS4	CSS3	CSS2	CSS1	CSS0	0000
AD1CON4	0332	—	—	—	—	—	—	—	—	—	—	—	—	—	DMABL<2:0>			0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-15: DAC1 REGISTER MAP FOR dsPIC33FJ128GP802/804 AND dsPIC33FJ64GP802/804

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
DAC1CON	03F0	DACEN	—	DACSIDL	AMPON	—	—	—	FORM	—	DACFDIV<6:0>							0000
DAC1STAT	03F2	LOEN	—	LMVOEN	—	—	LITYPE	LFULL	LEMPTY	ROEN	—	RMVOEN	—	—	RITYPE	RFULL	REMPTY	0000
DAC1DFLT	03F4	DAC1DFLT<15:0>																0000
DAC1RDAT	03F6	DAC1RDAT<15:0>																0000
DAC1LDAT	03F8	DAC1LDAT<15:0>																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

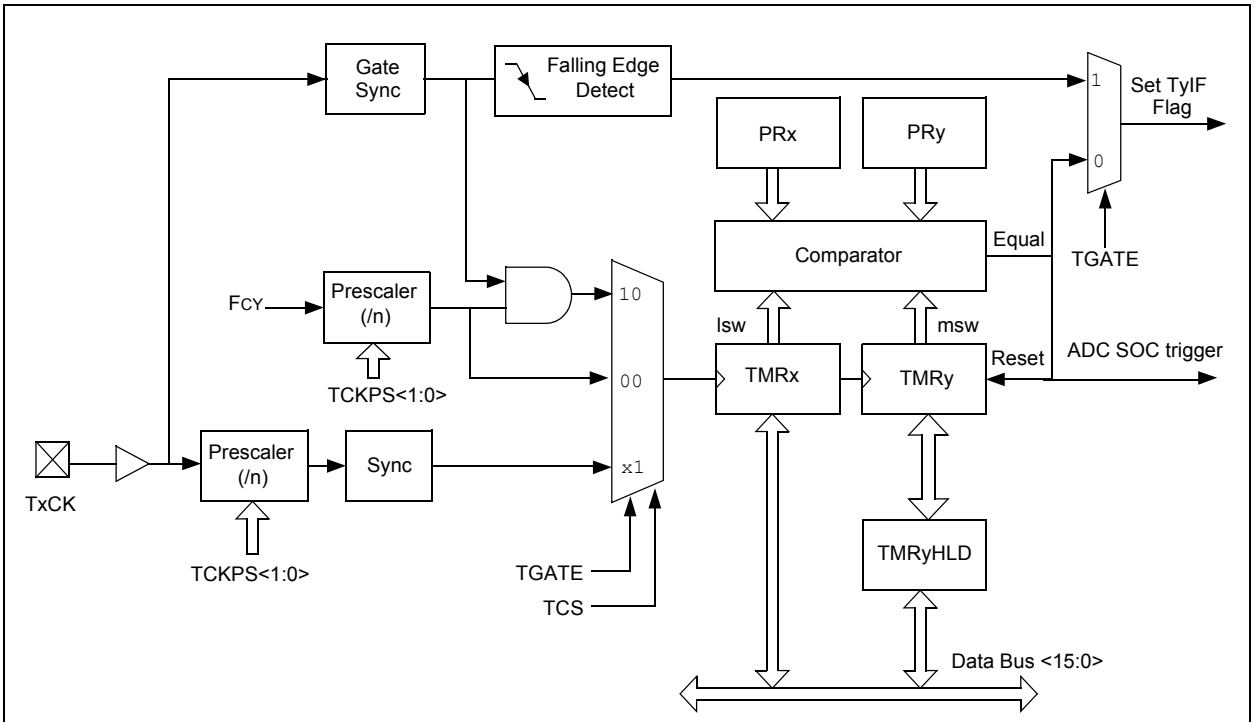
REGISTER 7-10: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0 (CONTINUED)

bit 2 **OC1IE:** Output Compare Channel 1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 1 **IC1IE:** Input Capture Channel 1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 0 **INT0IE:** External Interrupt 0 Flag Status bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

FIGURE 13-3: 32-BIT TIMER BLOCK DIAGRAM



Note 1: ADC trigger is available only on TMR3:TMR2 and TMR5:TMR2 32-bit timers.

2: Timer x is a Type B Timer (x = 2 and 4).

3: Timer y is a Type C Timer (y = 3 and 5).

13.3 Timer Resources

Many useful resources related to Timers are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en532311

13.3.1 KEY RESOURCES

- **Section 11. "Timers"** (DS70205)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

NOTES:

18.0 UNIVERSAL ASYNCHRONOUS RECEIVER TRANSMITTER (UART)

Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 17. "UART"** (DS70188) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Universal Asynchronous Receiver Transmitter (UART) module is one of the serial I/O modules available in the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 device family. The UART is a full-duplex asynchronous system that can communicate with peripheral devices, such as personal computers, LIN 2.0, RS-232 and RS-485 interfaces. The module also supports a hardware flow control option with the $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins and also includes an IrDA® encoder and decoder.

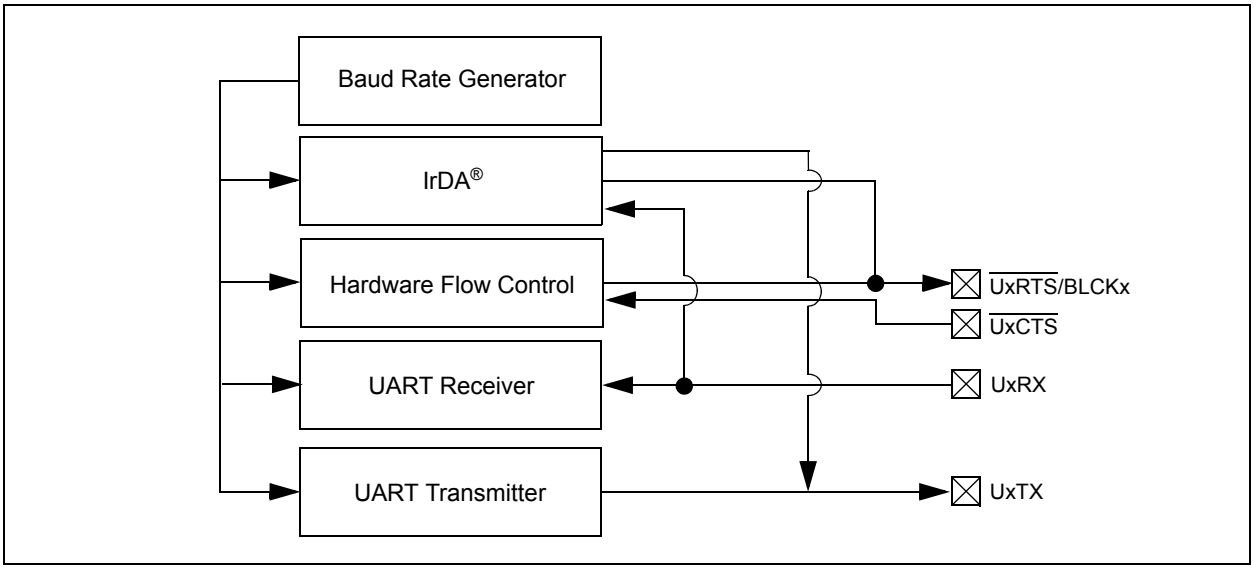
The primary features of the UART module are:

- Full-Duplex, 8-bit or 9-bit Data Transmission through the UxTX and UxRX pins
- Even, Odd or No Parity Options (for 8-bit data)
- One or two stop bits
- Hardware flow control option with $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins
- Fully integrated Baud Rate Generator with 16-bit prescaler
- Baud rates ranging from 10 Mbps to 38 bps at 40 MIPS
- 4-deep First-In First-Out (FIFO) Transmit Data buffer
- 4-deep FIFO Receive Data buffer
- Parity, framing and buffer overrun error detection
- Support for 9-bit mode with Address Detect (9th bit = 1)
- Transmit and Receive interrupts
- A separate interrupt for all UART error conditions
- Loopback mode for diagnostic support
- Support for sync and break characters
- Support for automatic baud rate detection
- IrDA® encoder and decoder logic
- 16x baud clock output for IrDA® support

A simplified block diagram of the UART module is shown in Figure 18-1. The UART module consists of these key hardware elements:

- Baud Rate Generator
- Asynchronous Transmitter
- Asynchronous Receiver

FIGURE 18-1: UART SIMPLIFIED BLOCK DIAGRAM



Note 1: Both UART1 and UART2 can trigger a DMA data transfer.

2: If DMA transfers are required, the UART TX/RX FIFO buffer must be set to a size of 1 byte/word (i.e., UTXISEL<1:0> = 00 and URXISEL<1:0> = 00).

BUFFER 19-5: ECAN™ MESSAGE BUFFER WORD 4

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 3							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 2							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 3<15:8>:** ECAN™ Message Byte 3

bit 7-0 **Byte 2<7:0>:** ECAN Message Byte 2

BUFFER 19-6: ECAN™ MESSAGE BUFFER WORD 5

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 5							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 4							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 5<15:8>:** ECAN™ Message Byte 5

bit 7-0 **Byte 4<7:0>:** ECAN Message Byte 4

REGISTER 26-3: PMADDR: PARALLEL PORT ADDRESS REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADDR15	CS1	ADDR<13:8>					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADDR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADDR15:** Parallel Port Destination Address bits

bit 14 **CS1:** Chip Select 1 bit
1 = Chip select 1 is active
0 = Chip select 1 is inactive

bit 13-0 **ADDR13:ADDR0:** Parallel Port Destination Address bits

REGISTER 26-4: PMAEN: PARALLEL PORT ENABLE REGISTER

U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	PTEN14	—	—	—	PTEN<10:8>(1)		
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTEN<7:2>(1)						PTEN<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **PTEN14:** PMCS1 Strobe Enable bit
1 = PMA14 functions as either PMA<14> bit or PMCS1
0 = PMA14 pin functions as port I/O

bit 13-11 **Unimplemented:** Read as '0'

bit 10-2 **PTEN<10:2>:** PMP Address Port Enable bits(1)
1 = PMA<10:2> function as PMP address lines
0 = PMA<10:2> function as port I/O

bit 1-0 **PTEN<1:0>:** PMALH/PMALL Strobe Enable bits
1 = PMA1 and PMA0 function as either PMA<1:0> or PMALH and PMALL
0 = PMA1 and PMA0 pads functions as port I/O

Note 1: Devices with 28 pins do not have PMA<10:2>.

TABLE 27-2: dsPIC CONFIGURATION BITS DESCRIPTION

Bit Field	Register	RTSP Effect	Description
BWRP	FBS	Immediate	Boot Segment Program Flash Write Protection 1 = Boot segment can be written 0 = Boot segment is write-protected
BSS<2:0>	FBS	Immediate	Boot Segment Program Flash Code Protection Size X11 = No Boot program Flash segment Boot space is 1K Instruction Words (except interrupt vectors) 110 = Standard security; boot program Flash segment ends at 0x0007FE 010 = High security; boot program Flash segment ends at 0x0007FE Boot space is 4K Instruction Words (except interrupt vectors) 101 = Standard security; boot program Flash segment, ends at 0x001FFE 001 = High security; boot program Flash segment ends at 0x001FFE Boot space is 8K Instruction Words (except interrupt vectors) 100 = Standard security; boot program Flash segment ends at 0x003FFE 000 = High security; boot program Flash segment ends at 0x003FFE
RBS<1:0>(1)	FBS	Immediate	Boot Segment RAM Code Protection Size 11 = No Boot RAM defined 10 = Boot RAM is 128 bytes 01 = Boot RAM is 256 bytes 00 = Boot RAM is 1024 bytes
SWRP(1)	FSS(1)	Immediate	Secure Segment Program Flash Write-Protect bit 1 = Secure Segment can bet written 0 = Secure Segment is write-protected
SSS<2:0>(1)	FSS(1)	Immediate	Secure Segment Program Flash Code Protection Size **(Secure segment is not implemented on 32K devices)** X11 = No Secure program flash segment Secure space is 4K IW less BS 110 = Standard security; secure program flash segment starts at End of BS, ends at 0x001FFE 010 = High security; secure program flash segment starts at End of BS, ends at 0x001FFE Secure space is 8K IW less BS 101 = Standard security; secure program flash segment starts at End of BS, ends at 0x003FFE 001 = High security; secure program flash segment starts at End of BS, ends at 0x003FFE Secure space is 16K IW less BS 100 = Standard security; secure program flash segment starts at End of BS, ends at 007FFEh 000 = High security; secure program flash segment starts at End of BS, ends at 0x007FFE

Note 1: This Configuration register is not available on dsPIC33FJ32GP302/304 devices.

TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.(3)	**Typical(2)**	**Max**	**Units**	**Conditions**		
Power-Down Current (I_{PD})(1)						
DC60d	24	68	µA	-40°C	3.3V	Base Power-Down Current(3,4)
DC60a	28	87	µA	+25°C		
DC60b	124	292	µA	+85°C		
DC60c	350	1000	µA	+125°C		
DC61d	8	13	µA	-40°C	3.3V	Watchdog Timer Current: ΔI_{WDT}(3,5)
DC61a	10	15	µA	+25°C		
DC61b	12	20	µA	+85°C		
DC61c	13	25	µA	+125°C		

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off (i.e., Sleep mode), oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled, all peripheral modules are disabled (PMDx bits are all '1's)
- RTCC is disabled
- JTAG is disabled

2: Data in the "Typ" column is at 3.3V, +25ºC unless otherwise stated.

3: The Watchdog Timer Current is the additional current consumed when the WDT module is enabled. This current should be added to the base I_{PD} current.

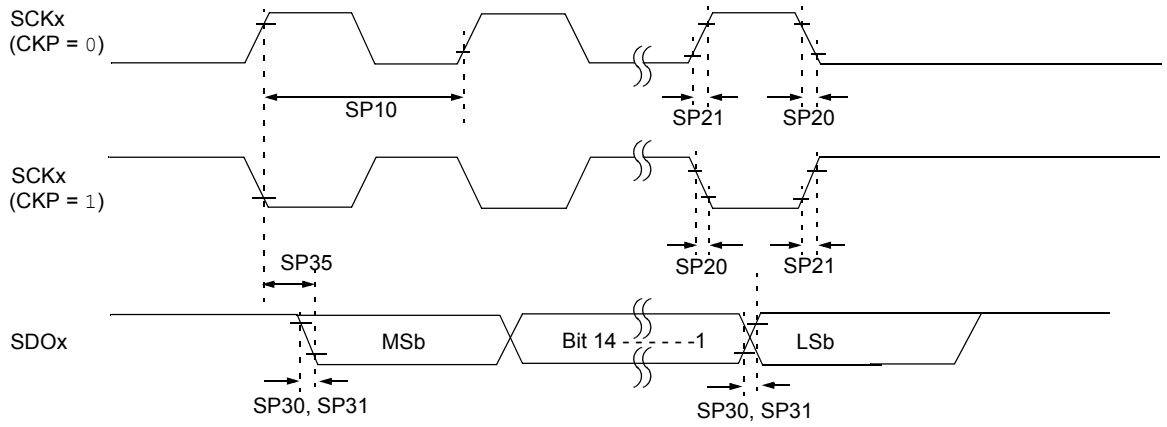
4: These currents are measured on the device containing the most memory in this family.

5: These parameters are characterized, but are not tested in manufacturing.

TABLE 30-28: SPIx MAXIMUM DATA/CLOCK RATE SUMMARY

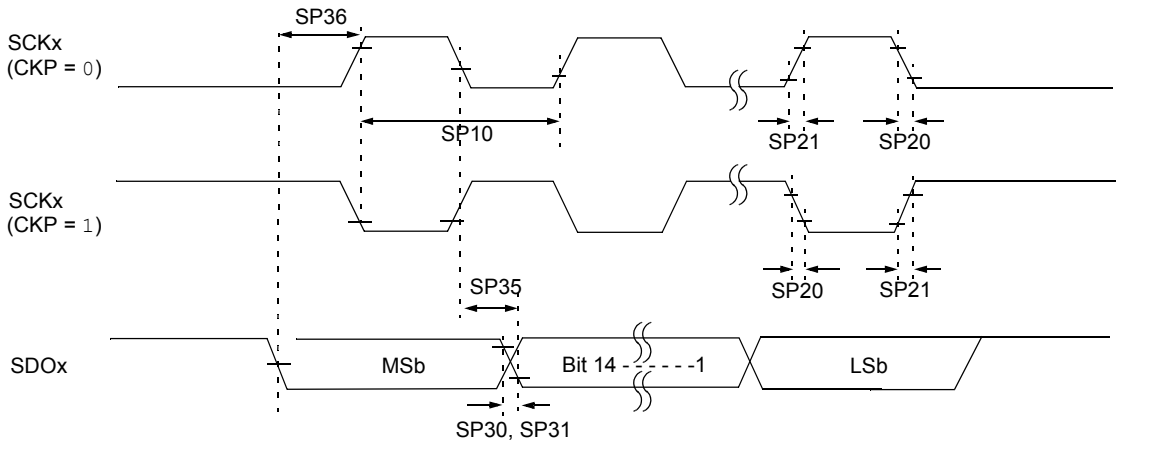
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 30-29	—	—	0,1	0,1	0,1
9 MHz	—	Table 30-30	—	1	0,1	1
9 MHz	—	Table 30-31	—	0	0,1	1
15 MHz	—	—	Table 30-32	1	0	0
11 MHz	—	—	Table 30-33	1	1	0
15 MHz	—	—	Table 30-34	0	1	0
11 MHz	—	—	Table 30-35	0	0	0

FIGURE 30-9: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

FIGURE 30-10: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-29: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCK Frequency	—	—	15	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdiV2scH, TdiV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—

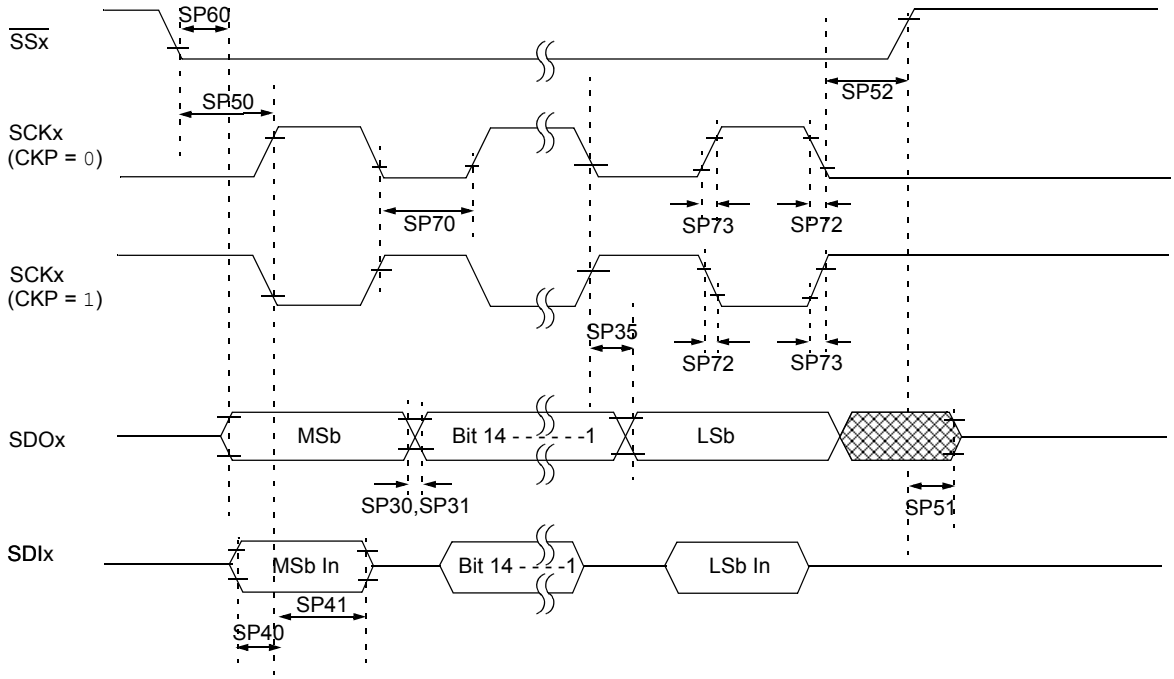
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 30-13: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-43: ADC MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
ADC Accuracy (10-bit Mode) – Measurements with external VREF+/VREF-							
AD20b	Nr	Resolution(1)	10 data bits			bits	—
AD21b	INL	Integral Nonlinearity	-1.5	—	+1.5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD22b	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD23b	GERR	Gain Error	—	3	6	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD24b	EOFF	Offset Error	—	2	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD25b	—	Monotonicity	—	—	—	—	Guaranteed
ADC Accuracy (10-bit Mode) – Measurements with internal VREF+/VREF-							
AD20b	Nr	Resolution(1)	10 data bits			bits	—
AD21b	INL	Integral Nonlinearity	-1	—	+1	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD22b	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD23b	GERR	Gain Error	3	7	15	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD24b	EOFF	Offset Error	1.5	3	7	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD25b	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (10-bit Mode)							
AD30b	THD	Total Harmonic Distortion	—	—	-64	dB	—
AD31b	SINAD	Signal to Noise and Distortion	57	58.5	—	dB	—
AD32b	SFDR	Spurious Free Dynamic Range	72	—	—	dB	—
AD33b	FNYQ	Input Signal Bandwidth	—	—	550	kHz	—
AD34b	ENOB	Effective Number of Bits	9.16	9.4	—	bits	—

Note 1: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

31.0 HIGH TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter DC10 in **Section 30.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 high temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(4) ..... -40°C to +150°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}(5) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 3.0V(5) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq$ 3.0V(5) ..... -0.3V to 5.6V
Maximum current out of V_{SS} pin ..... 60 mA
Maximum current into V_{DD} pin(2) ..... 60 mA
Maximum junction temperature ..... +155°C
Maximum current sourced/sunk by any 2x I/O pin(3) ..... 2 mA
Maximum current sourced/sunk by any 4x I/O pin(3) ..... 4 mA
Maximum current sourced/sunk by any 8x I/O pin(3) ..... 8 mA
Maximum current sunk by all ports combined ..... 70 mA
Maximum current sourced by all ports combined(2) ..... 70 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

3: Unlike devices at 125°C and below, the specifications in this section also apply to the CLKOUT, V_{REF+}, V_{REF-}, SCLx, SDAx, PGCx, and PGDx pins.

4: AEC-Q100 reliability testing for devices intended to operate at 150°C is 1,000 hours. Any design in which the total operating time from 125°C to 150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

5: Refer to the **"Pin Diagrams"** section for 5V tolerant pins.

TABLE 31-17: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Clock Parameters							
HAD50	TAD	ADC Clock Period(1)	147	—	—	ns	—
Conversion Rate							
HAD56	FCNV	Throughput Rate(1)	—	—	400	Ksps	—

Note 1: These parameters are characterized but not tested in manufacturing.

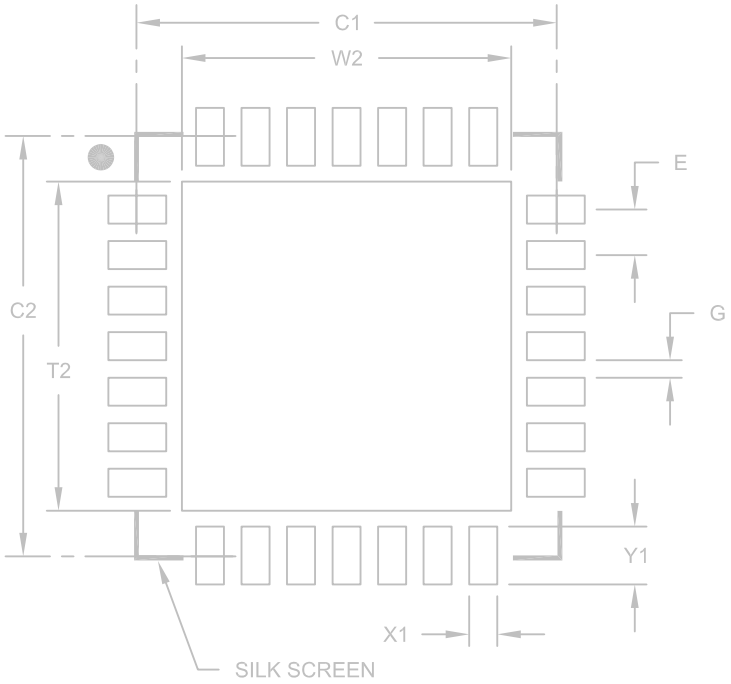
TABLE 31-18: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Clock Parameters							
HAD50	TAD	ADC Clock Period(1)	104	—	—	ns	—
Conversion Rate							
HAD56	FCNV	Throughput Rate(1)	—	—	800	Ksps	—

Note 1: These parameters are characterized but not tested in manufacturing.

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

Revision C (May 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

Global changes include:

- Changed all instances of OSCI to OSC1 and OSCO to OSC2
- Changed all instances of VDDCORE and VDDCORE/VCAP to VCAP/VDDCORE

The other changes are referenced by their respective section in the following table.

TABLE A-2: MAJOR SECTION UPDATES

Section Name	Update Description
High-Performance, 16-bit Digital Signal Controllers	Updated all pin diagrams to denote the pin voltage tolerance (see **"Pin Diagrams"**). Added Note 2 to the 28-Pin QFN-S and 44-Pin QFN pin diagrams, which references pin connections to VSS.
Section 1.0 "Device Overview"	Updated AVDD in the PINOUT I/O Descriptions (see Table 1-1). Added Peripheral Pin Select (PPS) capability column to Pinout I/O Descriptions (see Table 1-1).
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Added new section to the data sheet that provides guidelines on getting started with 16-bit Digital Signal Controllers.
Section 3.0 "CPU"	Updated CPU Core Block Diagram with a connection from the DSP Engine to the Y Data Bus (see Figure 3-1). Vertically extended the X and Y Data Bus lines in the DSP Engine Block Diagram (see Figure 3-3).
Section 4.0 "Memory Organization"	Updated Reset value for CORCON in the CPU Core Register Map (see Table 4-1). Updated the Reset values for IPC14 and IPC15 and removed the FLTA1IE bit (IEC3) from the Interrupt Controller Register Map (see Table 4-4). Updated bit locations for RPINR25 in the Peripheral Pin Select Input Register Map (see Table 4-21). Updated the Reset value for CLKDIV in the System Control Register Map (see Table 4-33).
Section 5.0 "Flash Program Memory"	Updated **Section 5.3 "Programming Operations"** with programming time formula.
Section 9.0 "Oscillator Configuration"	Updated the Oscillator System Diagram and added Note 2 (see Figure 9-1). Added Note 1 and Note 2 to the OSCON register (see Register 9-1). Updated default bit values for DOZE<2:0> and FRCDIV<2:0> in the Clock Divisor (CLKDIV) Register (see Register 9-2). Added a paragraph regarding FRC accuracy at the end of **Section 9.1.1 "System Clock Sources"**. Added Note 3 to **Section 9.2.2 "Oscillator Switching Sequence"**. Added Note 1 to the FRC Oscillator Tuning (OSCTUN) Register (see Register 9-4).

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	Updated Typical values for Thermal Packaging Characteristics (see Table 30-3). Updated Min and Max values for parameter DC12 (RAM Data Retention Voltage) and added Note 4 (see Table 30-4). Updated Power-Down Current Max values for parameters DC60b and DC60c (see Table 30-7). Updated Characteristics for I/O Pin Input Specifications and added parameter DI21 (see Table 30-9). Updated Program Memory values for parameters 136, 137, and 138 (renamed to 136a, 137a, and 138a), added parameters 136b, 137b, and 138b, and added Note 2 (see Table 30-12). Added parameter OS42 (GM) to the External Clock Timing Requirements (see Table 30-16). Updated Watchdog Timer Time-out Period parameter SY20 (see Table 30-21). Updated the IREF Current Drain parameter AD08 (see Table 30-37). Updated parameters AD30a, AD31a, AD32a, AD33a, and AD34a (see Table 30-38) Updated parameters AD30b, AD31b, AD32b, AD33b, and AD34b (see Table 30-39)